# **Surface Mount Ultrafast Power Rectifiers**

MURS105T3G, MURS110T3G, MURS115T3G, MURS120T3G, MURS140T3G, MURS160T3G, SURS8105T3G, SURS8110T3G, SURS8115T3G, SURS8120T3G, SURS8140T3G, SURS8160T3G

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

#### **Features**

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.71 to 1.05 V Max @ 1.0 A,  $T_J = 150^{\circ}$ C)
- AEC-Q101 Qualified and PPAP Capable
- SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These are Pb-Free Packages

### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 95 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

1

- Polarity: Polarity Band Indicates Cathode Lead
- ESD Rating:
  - Human Body Model = 3B (> 8 kV)
  - ◆ Machine Model = C (> 400 V)



# ON Semiconductor®

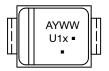
http://onsemi.com

# ULTRAFAST RECTIFIERS 1.0 AMPERE, 50-600 VOLTS



SMB CASE 403A

#### **MARKING DIAGRAM**



A = Assembly Location\*

′ = Year

WW = Work Week

U1 = Device Code

x = A, B, C, D, G, or J

= Pb-Free Package(Note: Microdot may be in either location)

\* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

### ORDERING INFORMATION

See detailed ordering and shipping information in the table on page 2 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking table on page 2 of this data sheet.

#### **MAXIMUM RATINGS**

		MURS/SURS8						
Rating	Symbol	105T3	110T3	115T3	120T3	140T3	160T3	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	50	100	150	200	400	600	V
Average Rectified Forward Current	I <sub>F(AV)</sub>				1.0 @ T <sub>L</sub> 2.0 @ T <sub>L</sub>		Α	
Non-Repetitive Peak Surge Current, (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	40 35		5	Α			
Operating Junction Temperature	TJ	- 65 to +175			°C			

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

# THERMAL CHARACTERISTICS

		MURS/SURS8						
Rating	Symbol	105T3	110T3	115T3	120T3	140T3	160T3	Unit
Thermal Resistance Junction-to-Lead (T <sub>L</sub> = 25°C)	$R_{ heta JL}$	13		°C/W				

#### **ELECTRICAL CHARACTERISTICS**

Maximum Instantaneous Forward Voltage (Note 1) ( $i_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C}$ ) ( $i_F = 1.0 \text{ A}, T_J = 150^{\circ}\text{C}$ )	VF	0.875 0.71	1.25 1.05	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, T <sub>J</sub> = 25°C) (Rated DC Voltage, T <sub>J</sub> = 150°C)	i <sub>R</sub>	2.0 50	5.0 150	μА
Maximum Reverse Recovery Time ( $i_F = 1.0$ A, di/dt = 50 A/ $\mu$ s) ( $i_F = 0.5$ A, $i_R = 1.0$ A, $I_R$ to 0.25 A)	t <sub>rr</sub>	35 25	75 50	ns
Maximum Forward Recovery Time (i <sub>F</sub> = 1.0 A, di/dt = 100 A/μs, Rec. to 1.0 V)	t <sub>fr</sub>	25	50	ns
Typical Peak Reverse Recovery Current (I <sub>F</sub> = 1.0 A, di/dt = 50 A/μs)	I <sub>RM</sub>	0.75	1.60	Α

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

# **DEVICE MARKING AND ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
MURS105T3G, SURS8105T3G	U1A	SMB (Pb-Free)	2,500 Units / Tape & Reel
MURS110T3G, SURS8110T3G	U1B	SMB (Pb-Free)	2,500 Units / Tape & Reel
MURS115T3G, SURS8115T3G	U1C	SMB (Pb-Free)	2,500 Units / Tape & Reel
MURS120T3G, SURS8120T3G	U1D	SMB (Pb-Free)	2,500 Units / Tape & Reel
MURS140T3G, SURS8140T3G	U1G	SMB (Pb-Free)	2,500 Units / Tape & Reel
MURS160T3G, SURS8160T3G	U1J	SMB (Pb-Free)	2,500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MURS105T3G, MURS110T3G, MURS115T3G, MURS120T3G, SURS8105T3G, SURS8110T3G, SURS8115T3G, SURS8120T3G

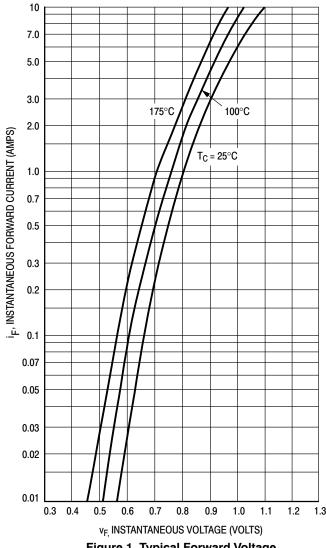


Figure 1. Typical Forward Voltage

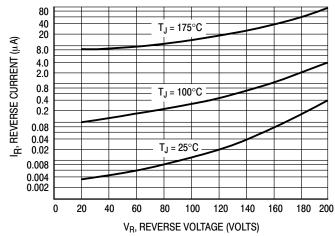


Figure 2. Typical Reverse Current\*

\*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied V<sub>R</sub> is sufficiently below rated V<sub>R</sub>.

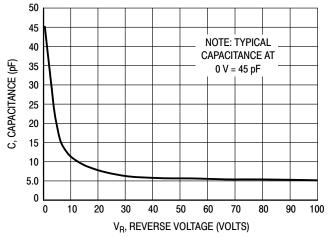


Figure 3. Typical Capacitance

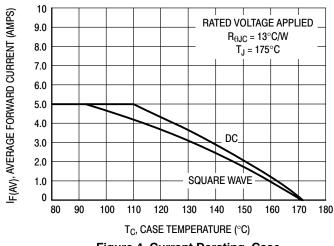


Figure 4. Current Derating, Case

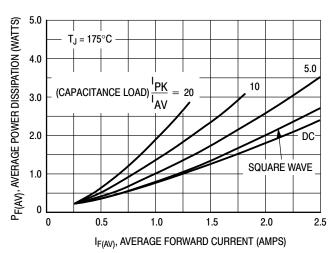
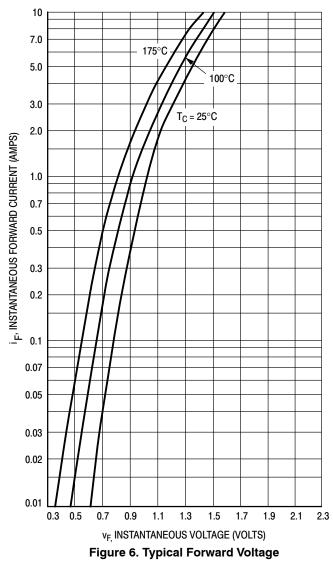


Figure 5. Power Dissipation

# MURS140T3G, MURS160T3G, SURS8140T3G, SURS8160T3G



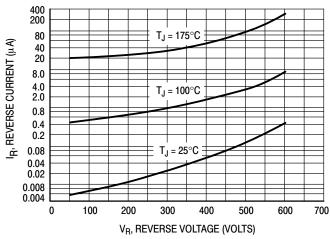


Figure 7. Typical Reverse Current\*

\*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied  $V_R$  is sufficiently below rated  $V_R$ .

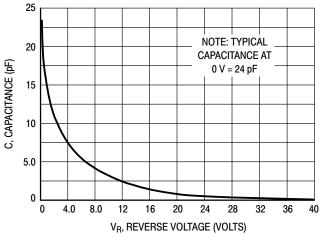


Figure 8. Typical Capacitance

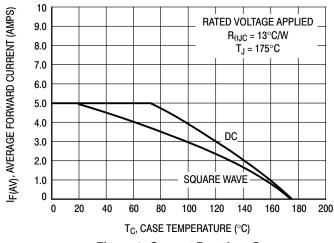


Figure 9. Current Derating, Case

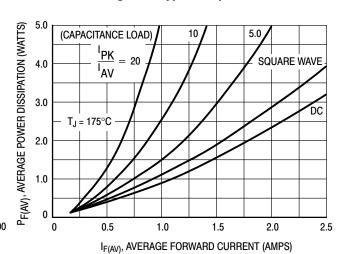
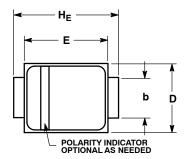


Figure 10. Power Dissipation

#### PACKAGE DIMENSIONS

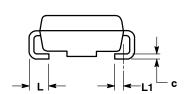
#### **SMB** CASE 403A-03 **ISSUE J**

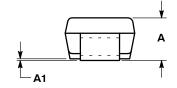




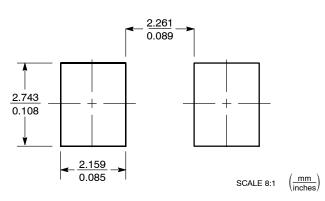
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION: INCH.
- DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.95	2.30	2.47	0.077	0.091	0.097	
A1	0.05	0.10	0.20	0.002	0.004	0.008	
b	1.96	2.03	2.20	0.077	0.080	0.087	
С	0.15	0.23	0.31	0.006	0.009	0.012	
D	3.30	3.56	3.95	0.130	0.140	0.156	
E	4.06	4.32	4.60	0.160	0.170	0.181	
HE	5.21	5.44	5.60	0.205	0.214	0.220	
L	0.76	1.02	1.60	0.030	0.040	0.063	
L1	0.51 REF			0.020 REF			





#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and iii) are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all Claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

# LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative